

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet



SMA

**Features**

- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- Glass passivated chip junction
- For surface mount application
- Low profile package
- Built-in strain relief, ideal for automated placement

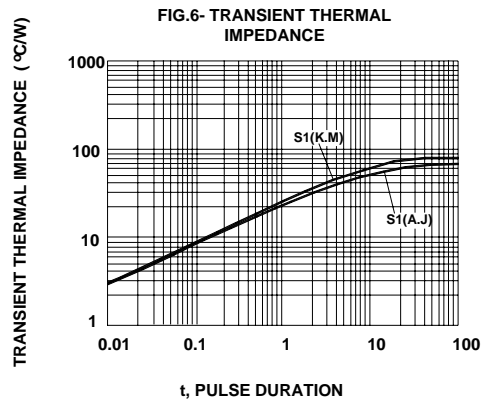
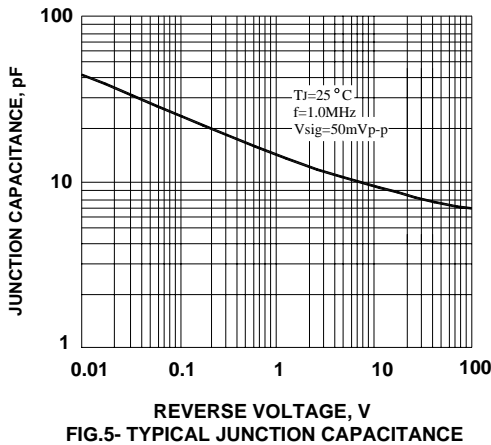
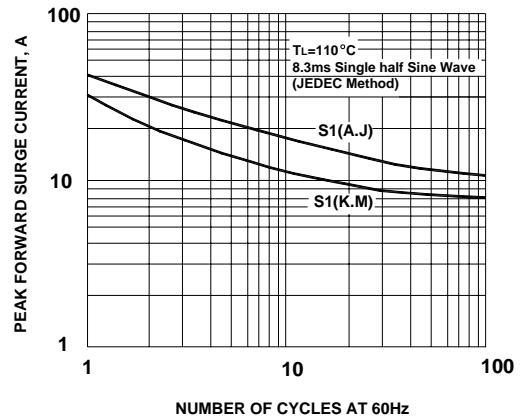
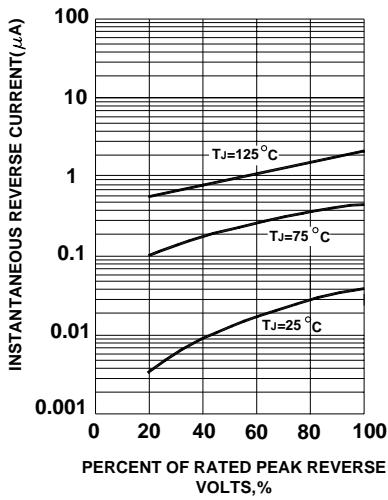
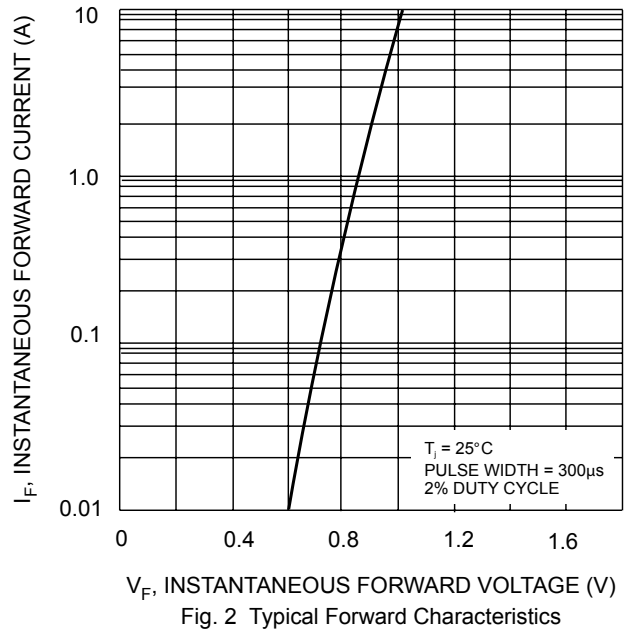
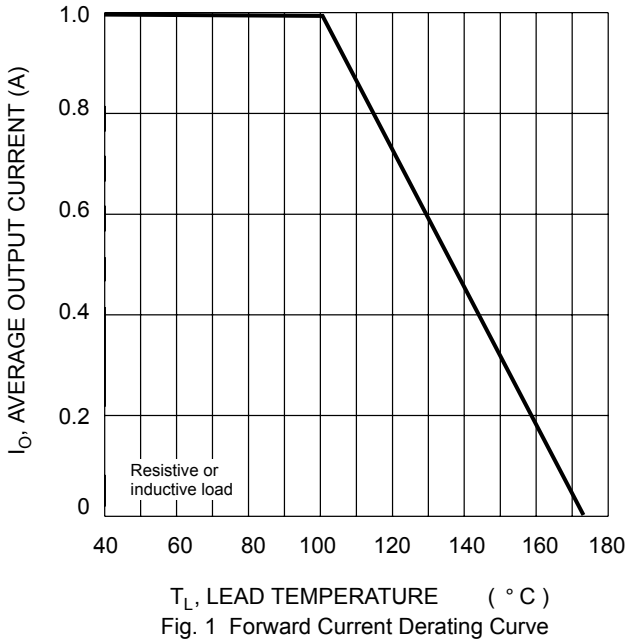
**Mechanical Data**

- **Case:** SMA (DO-214AC), molded plastic
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end

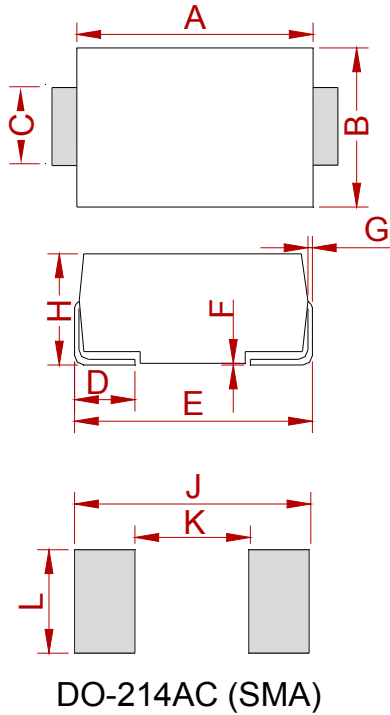
**Maximum Ratings and Electrical Characteristics** @ $T_A=25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	$V_{RWM}$								
DC Blocking Voltage	$V_R$								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_L = 100^\circ\text{C}$	$I_O$	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30							A
Forward Voltage @ $I_F = 1.0\text{A}$	$V_{FM}$	1.10							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	$I_{RM}$	5.0 200							$\mu\text{A}$
Typical Junction Capacitance (Note 2)	$C_j$	15							pF
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$	30							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-65 to +175							$^\circ\text{C}$

Note: 1. Measured with  $I_F = 0.5\text{A}$ ,  $I_R = 1.0\text{A}$ ,  $I_{rr} = 0.25\text{A}$ ,  
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.  
 3. Mounted on P.C. Board with 8.0mm<sup>2</sup> land area.



**PACKAGE MECHANICAL DATA**



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

**REEL SPECIFICATION**

P/N	PKG	QTY
S1A THRU S1M	SMA	2000

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